



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

* : *Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-28
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STU7LN80K5	TSIK*VK8GB5F	A	998G	2017-04-28
	Amount	UoM	Unit type	ST ECOPACK Grade
	310.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	6.1-6.5-2.3	3	Through-hole	
Comment	IPAK TO-251			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	2.38	die backside metal-leadframe metal	7665
Lead	4.59	soft solder	14810

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TSIK*VK8GB5F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.930	mg	supplier	die	Silicon (Si)	7440-21-3		3.672	mg	934351	11845
				supplier	metallization	Aluminium (Al)	7429-90-5		0.096	mg	24427	310
				supplier	metallization	Copper (Cu)	7440-50-8		0.035	mg	8907	113
				supplier	Passivation	Silicon Nitride	12033-89-5		0.022	mg	5598	71
				supplier	Passivation	Silicon Oxide	7631-86-9		0.055	mg	13995	177
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	763	10
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.035	mg	8906	113
Leadframe	Copper & its alloys	184.073	mg	supplier	back side metallization	Silver (Ag)	7440-22-4		0.012	mg	3053	39
				supplier	alloy	Copper (Cu)	7440-50-8		181.550	mg	986293	585645
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.182	mg	989	587
				supplier	metallization	Nickel (Ni)	7440-02-0		2.341	mg	12718	7552
Soft solder	Solder	4.807	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	4.591	mg	955066	14810
				supplier	solder	Silver (Ag)	7440-22-4		0.120	mg	24964	387
				supplier	solder	Tin (Sn)	7440-31-5		0.096	mg	19970	310
Bonding wires	Other inorganic materials	1.094	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.094	mg	1000000	3527
				supplier	mold compound	Silica, vitreous	60676-86-0		97.782	mg	870001	315426
Encapsulation	Other Organic Materials	112.393	mg	supplier	mold compound	Epoxy resin	25068-38-6		11.239	mg	99997	36255
				supplier	mold compound	Phenol resin	29690-82-2		2.810	mg	25002	9065
				supplier	mold compound	Carbon Black	1333-86-4		0.562	mg	5000	1813
				supplier	mold compound	Carbon Black	1333-86-4		0.562	mg	5000	1813
Connections coating	Solder	3.703	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.703	mg	1000000	11945